

REMARKS

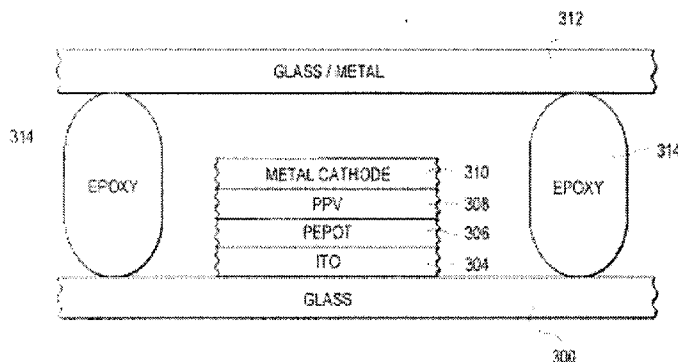
In reply to the Office Action of June 5, 2006, Applicant submits the following remarks. Claims 1, 2 and 46 have been amended. Claim 1 was amended to correct a typographical error. Claim 2 was amended to provide antecedent support for the cap. Support for the amendment to claim 46 can be found in figure 2 and the accompanying text. Claim 46 has been amended to clarify the relationship between the spacer particles and the second electrode. Applicant respectfully requests reconsideration in view of the foregoing amendment and these remarks.

Section 102 Rejections

Claims 46 and 48 were rejected under 35 U.S.C. 102(b) as allegedly being anticipated by U.S. Patent Number 6,659,706 ("Pakbaz"). Applicant disagrees.

Claim 46 requires spacer particles.

Pakbaz describes an OLED display 300 having epoxy 314 (FIG. 3, col. 2, line 50-col. 3 line 51). The epoxy 314 is deposited along the outer edges of the display area to adhere the foil 312 to the glass. FIG. 3 is reproduced below for the Examiner's convenience.



Pakbaz fails to suggest or disclose spacer particles. What Pakbaz shows is an epoxy that is deposited around the outer edges of the display area. Although in cross section the epoxy 314 may appear to be a particle, it is not a particle, but rather a continuous structure. For at least this

reason, Pakbaz fails to anticipate claim 46. Claim 48 depends from claim 46 and is not anticipated for at least the same reason.

Section 103 Rejections

Claims 1, 2, 3/1, 3/2, 4-11, 14/1, 14/2-19 and 43-45 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Pakbaz in view of JP 03171643 ("Nakao"). The applicant respectfully disagrees.

Claims 1 and 2 require spacer particles.

Nakao describes a semiconductor chip 5 with bumps 2 and electrodes 4 on what appears to be a flip chip (Figure 4, abstract). The bumps 2 are likely solder bumps that have a domed or bubble shape with one flattened side, with the shape being formed by melting and cooling of the solder material. The bumps 2 serve as electrical contacts between the electrodes 4 on a substrate and a chip 5 (Figure 11).

As noted above, Pakbaz does not describe spacer particles. Nakao also does not disclose spacer particles. What Nakao describes are electrical contacts, or solder bumps. Applicant submits that there is no motivation to add solder bumps to an OLED, as described by Pakbaz. For at least this reason, applicant submits that no *prima facie* case of obviousness has been made with respect to claims 1 or 2. Claims 3-11, 14-19 and 43-45 depend from claims 1 or 2 and are not obvious over the combination of Pakbaz and Nakao for at least the same reasons.

Allowable Claims

Applicant thanks the Examiner for merely objecting to claims 12, 13, 20, 21 and 47 and finding that they would be allowable if rewritten in independent form.

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No fee is believed to be due. If, however, there are any charges or credits, please apply them to Deposit Account No. 06-1050.

Respectfully submitted,

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